

#### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	Rds(on) max	I <sub>D MAX</sub> T <sub>A</sub> = +25°C
20V	9.5mΩ @ V <sub>GS</sub> = 4.5V	11.7A
200	11mΩ @ V <sub>GS</sub> = 2.5V	10.8A

## **Description**

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

# **Applications**

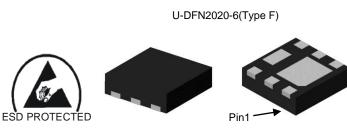
- · General Purpose Interfacing Switch
- Power Management Functions

### **Features**

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. <a href="https://www.diodes.com/quality/product-definitions/">https://www.diodes.com/quality/product-definitions/</a>

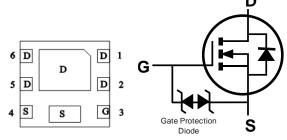
### **Mechanical Data**

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.0065 grams (Approximate)



Top View

Bottom View



Pin Out Bottom View

**Equivalent Circuit** 

## Ordering Information (Note 4)

Part Number	Case	Reel Size (inches)	Quantity per Reel
DMN2011UFDF-7	U-DFN2020-6 (Type F)	7	3,000
DMN2011UFDF-13	U-DFN2020-6 (Type F)	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

Site 1



N2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Year	2016		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D		Н	I	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



D5 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = week 27; z represents week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2016	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	6	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note C) \/ 45\/	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	l <sub>D</sub>	11.7 9.3	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	l <sub>D</sub>	14.2 11.4	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	s)		I <sub>DM</sub>	80	Α
Maximum Body Diode Continuous Current		Is	2.5	Α	
Avalanche Current (Notes 7) L = 0.1mH	I <sub>AS</sub>	18	А		
Avalanche Energy (Notes 7) L = 0.1mH			Eas	17	mJ

# **Thermal Characteristics**

Characteristic		Symbol	Value	Unit	
Total Bower Discipation (Note 5)	$T_A = +25$ °C	D-	0.73	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.47	VV	
Thormal Posistance Junction to Ambient (Note 5)	Steady State	D	175	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	128	C/VV	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	D-	2.1	W	
Total Fower Dissipation (Note 6)	$T_A = +70^{\circ}C$	$P_{D}$	1.3	VV	
Thormal Posistanas Junction to Ambient (Note 6)	Steady State	D	61		
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	45	°C/W	
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	9.3		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

# **Electrical Characteristics** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)					l .	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	_	_	1	μΑ	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 10V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.4		1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
			6.5	9.5		$V_{GS} = 4.5V, I_{D} = 7A$
Static Drain-Source On-Resistance	D		7.5	11	mΩ	$V_{GS} = 2.5V, I_{D} = 7A$
Static Drain-Source On-Resistance	RDS(ON)	_	10	20	11122	$V_{GS} = 1.8V, I_D = 5A$
			15	35		$V_{GS} = 1.5V, I_{D} = 3A$
Diode Forward Voltage	VsD	_	0.7	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 8.5A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	2248	_	pF	10)()(
Output Capacitance	Coss		295	_	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1.0MHz
Reverse Transfer Capacitance 4	Crss	_	265	_	pF	1 = 1.0WH IZ
Gate Resistance	Rg	_	1.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	24	_	nC	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	56	_	nC	101/ 1 0.54
Gate-Source Charge	Qgs	_	3.5	_	nC	$V_{DS} = 10V, I_{D} = 8.5A$
Gate-Drain Charge	Qgd	_	5.1	_	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.6	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	2.6	_	ns	V <sub>DS</sub> = 10V, I <sub>D</sub> = 8.5A
Turn-Off Delay Time	tD(OFF)	_	21.6	_	ns	$V_{GS} = 4.5V, R_g = 1.8\Omega$
Turn-Off Fall Time	t <sub>F</sub>	_	13.5	_	ns	7
Reverse Recovery Time	T <sub>RR</sub>	_	12.8	_	ns	L 0.5A 41/44 040A/
Reverse Recovery Charge	Q <sub>RR</sub>	_	6.9	_	nC	I <sub>F</sub> = 8.5A, di/dt = 210A/μs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

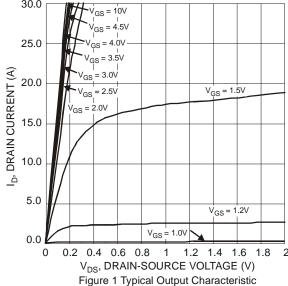
<sup>7.</sup>  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.

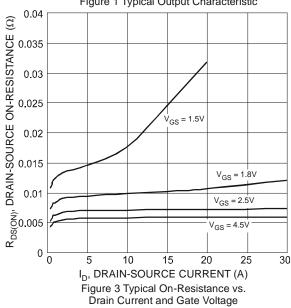
<sup>8.</sup> Short duration pulse test used to minimize self-heating effect.

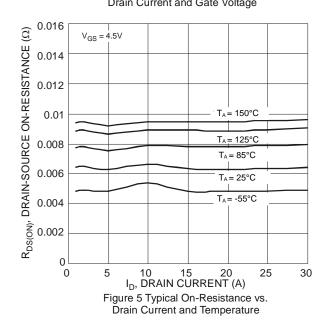
<sup>9.</sup> Guaranteed by design. Not subject to product testing.

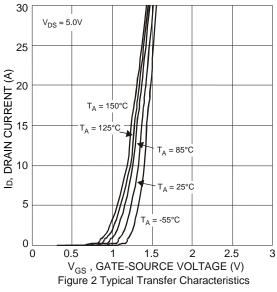


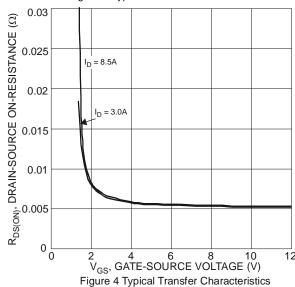












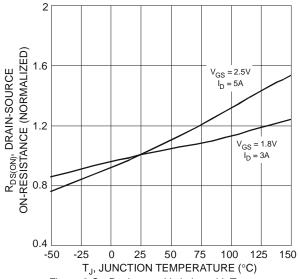
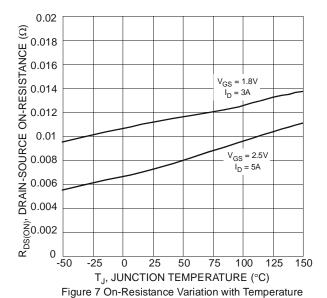
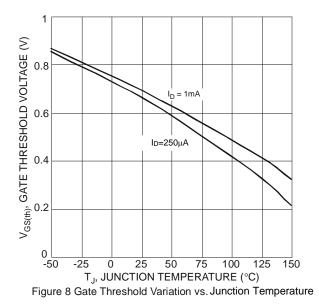
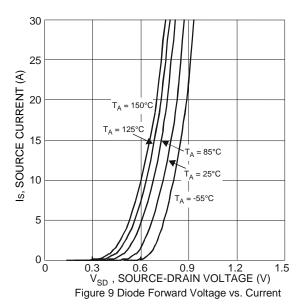


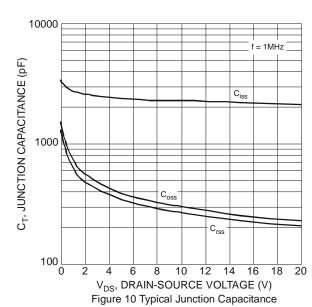
Figure 6 On-Resistance Variation with Temperature

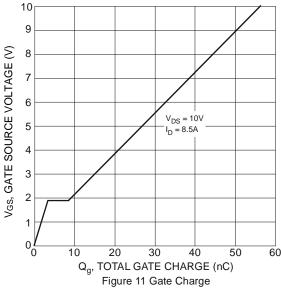


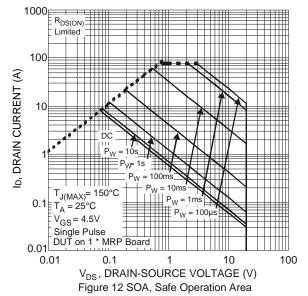




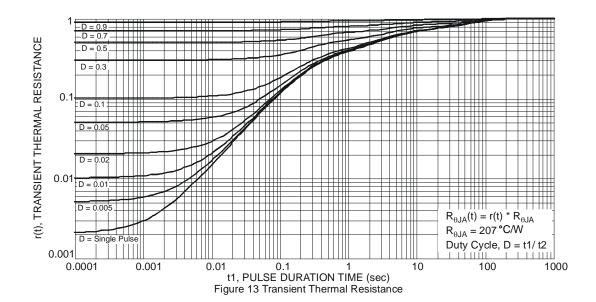










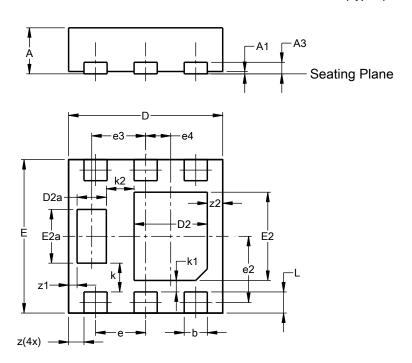




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)

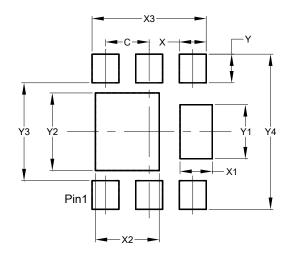


U-DFN2020-6						
	(Ту	oe F)				
Dim	Min	Max	Тур			
Α	0.57	0.63	0.60			
A1	0.00	0.05	0.03			
A3	-	-	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.85	1.05	0.95			
D2a	0.33	0.43	0.38			
Е	1.95	2.05	2.00			
E2	1.05	1.25	1.15			
E2a	0.65	0.75	0.70			
е		0.65 BS	С			
e2	(	).863 BS	SC			
е3		0.70 BS				
e4	(	).325 BS	SC .			
k		0.37 BS	С			
k1		0.15 BS				
k2		0.36 BS	O			
L	0.225 0.325 0.275					
Z	0.20 BSC					
<b>z</b> 1	0.110 BSC					
z2		0.20 BS	С			
All C	Dimens	ions in	mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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